

## CLAIMS

What is claimed is:

1. (Currently Amended) A semiconductor package comprising:
  - a leadframe having a flag and a bond pad;
  - a semiconductor die attached to the flag and electrically coupled to the bond pad;
  - a mold encapsulant over the semiconductor die;
  - a conductive layer over the mold encapsulant, wherein the conductive layer comprises a ferromagnetic material; and
  - a wire electrically coupling the leadframe to the conductive layer.
2. (Canceled) The semiconductor package of claim 1, wherein the conductive layer comprises a ferromagnetic material.
3. (Original) The semiconductor package of claim 2, wherein the conductive layer comprises NiFe.
4. (Original) The semiconductor package of claim 1, wherein the conductive layer comprises an element selected from the group consisting of aluminum, copper, tin and zinc.
5. (Original) The semiconductor package of claim 1, wherein the conductive layer comprises a ferromagnetic material and a nonferromagnetic metal.
6. (Currently Amended) The semiconductor package of claim 1, wherein the wire is coupled to the leadframe through the semiconductor die ~~and wire bonds~~.
7. (Original) The semiconductor package of claim 1, wherein the wire is coupled to the leadframe through a pad.
8. (Previously Amended) The semiconductor package of claim 1, wherein the conductive layer is an electromagnetic shield.

9-19. Canceled.

20. (Currently Amended) A method of forming a semiconductor package, the method comprising:

providing a leadframe having a flag;  
 attaching a semiconductor die to the flag;  
 forming a mold encapsulant over the semiconductor die;  
 forming a conductive layer over the mold encapsulant, wherein forming a conductive layer further comprises electrically coupling the conductive layer to the wire; and  
 electrically coupling the leadframe to the conductive layer using a wire, wherein electrically coupling the leadframe to the conductive layer using a wire further comprises:  
providing a wire having a first end and a second end;  
electrically coupling the first end and the second end of the wire to the semiconductor die; and  
removing a portion of the mold encapsulant to expose a portion of the wire.

21. (Canceled) The method of claim 20, wherein:

electrically coupling the leadframe to the conductive layer using a wire further comprises:  
 providing a wire having a first end and a second end;  
 electrically coupling the first end and the second end of the wire to the semiconductor die; and  
 removing a portion of the mold encapsulant to expose a portion of the wire;  
 and  
 forming a conductive layer over further comprises:  
 electrically coupling the conductive layer to the wire.

22. (Currently Amended) The method of claim 20, wherein:

forming a mold encapsulant over the semiconductor die, further comprises forming the mold encapsulant over the wire; ~~and~~  
~~forming a conductive layer over the mold encapsulant further comprises electrically coupling the conductive layer to the wire; and~~  
~~the method further comprises:~~  
~~removing the mold encapsulant to expose the wire.~~

23. (Original) The method of claim 22, wherein removing the mold encapsulant to expose the wire further comprises forming a groove in the mold encapsulant, wherein the groove has sidewalls.

24. (Original) The method of claim 23, wherein forming the conductive layer further comprises forming the conductive layer over the sidewalls of the groove.